

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chun Seok JEONG	05/21/2011
Jae Jin LEE	05/21/2011
RECEIVING PARTY DATA	
Name:	Hynix Semiconductor Inc.
Street Address:	San 136-1, Ami-ri, Bubal-eub
City:	Ichon-shi
State/Country:	REPUBLIC OF KOREA
Postal Code:	467-860
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13162676
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Total Attachments: 2 source=144-11-Assignment#page1.tif source=144-11-Assignment#page2.tif	

OP \$40.00 13162676

ASSIGNMENT

WHEREAS, We, the below named inventors (hereinafter referred to as "Assignors"), have made an invention entitled:

SEMICONDUCTOR APPARATUS, METHOD FOR ASSIGNING CHIP IDS THEREIN, AND METHOD FOR SETTING CHIP IDS THEREOF

for which we executed an application for United States Letters Patent

- concurrently herewith, or
- filed as Application No. _____ on _____, and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"), organized and operating under the laws of Republic of Korea, whose post office address is San 136-1, Ami-ri, Bubal-eub, Ichon-si, Gyeonggi-do 467-860, Republic of Korea, is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the letters Patent to be issues upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, Assignors have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto Assignee, its lawful successors and assigns, the entire right, title, and interest in and to this invention, this application, all divisions and continuations thereof, all Letters Patent of the United States which may be granted thereon, all reissues thereof, all rights to claim priority on the basis of this application, all applications for Letters Patent which may hereafter be filed for this invention in any foreign country, all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and Assignors hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, ASSIGNORS HEREBY covenant that Assignor has the full right to convey the interest assigned by this Assignment, and Assignors have not executed and will not execute any agreement in conflict with this Assignment;

AND, ASSIGNORS HEREBY further covenant and agree, without further consideration, that Assignors will communicate with Assignee, its successors and assigns, any facts known to Assignors respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for

this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, We have hereunto set our hands.

Signature of Inventor: Chunseok Jeong

Inventor(s) Name: JEONG, Chun Seek

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: 2011. 5. 21

Signature of Inventor: LEE, JAE JIN

Inventor(s) Name: LEE, Jae Jin

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Citizenship: Korean

Date: 2011. 5. 21
